

Soldered SAM data sheet SAM- λ -A- τ -4.0-12.7s-c or SAM- λ -A- τ -4.0-12.7s-e

SAM chip area standard: 4.0 mm x 4.0 mm

optional: other dimensions on request

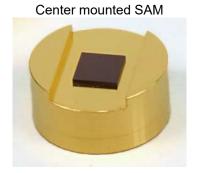
Chip thickness standard: 450 µm

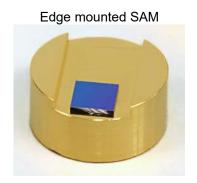
Front side protection The SAM is protected with a dielectric front layer.

The SAM chip is soldered on a gold plated Cu-cylinder with \emptyset 12.7 mm. The solder provides a low thermal resistance between the SAM and the mount.

- The **standard** position of the SAM is in the center of the mount \rightarrow x = 4.0-12.7s-c.
- Optional the SAM can be soldered at the edge of the mount without extra charges

 \rightarrow x = 4.0-12.7s-e.





Dimensions:

